

## **AMENDMENTS TO THE SPECIFICATION**

**Please amend paragraph [0060] beginning on page 10, as follows:**

[0060] As best seen in FIG. 1B, there may be a layer 48 of electrically conductive attachment material disposed between element 42 and distal end 34 of leadframe 12. There may also be a layer 50 of electrically conductive attachment material disposed between element 44 and distal end 36 (FIG. 1A) of leadframe 14. The die attachment material of layers 38, 40, 48, 50 may be a type of solder paste, solder preform, ultra-thick thick film (UTTFF), or electrically conductive adhesive, for example.

**Please amend paragraph [0066] beginning on page 12, as follows:**

[0066] As best seen in FIG. 3D, while considering FIGS. 3A-3C, each of members 82a-g is bent at an angle of 90° such that distal ends 86a-g of members 82a-g extend in a direction perpendicular to body 80. As also seen in FIG. 3D, members 82a-g define an imaginary plane 94. As best seen in FIG. 3C, each of members 82a-g follows a bending path, i.e., is nonlinear, in a direction within plane 94.